

## LUNAR RECONNAISSANCE ORBITER PROJECT CONFIGURATION CHANGE REQUEST

CCR: 431-CCR-000105	DATE INITIATED: 2/2/2006	CCR REV.:	CCR REV DATE: _____
CCB SECRETARY: DEB YODER	PROPRIETARY? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	ITAR SENSITIVE? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	CCR DUE DATE: 2/14/2006
CCR TITLE (Brief Description): REVISE THE THERMAL SYSTEMS SPECIFICATION TO INCLUDE LATEST UPDATES (I.E., TEMPERATURE CHANGES)			
ORIGINATOR NAME: <u>Charles Baker</u> E-MAIL: <u>Charles.Baker@nasa.gov</u>		CODE/ORG.: <u>545/GSFC</u> PHONE: <u>301-286-2065</u>	
SPONSOR NAME: <u>Charles Baker</u> E-MAIL: <u>Charles.Baker@nasa.gov</u>		CODE/ORG.: <u>545/GSFC</u> PHONE: <u>301-286-2065</u>	
EXTERNAL ORGANIZATION CCR#:		EXTERNAL ORGANIZATION:	
DOCUMENT (INCLUDE THE DOC. # AND TITLE), CONTRACT, SOFTWARE AFFECTED: 431-SPEC-000091 LUNAR RECONNAISSANCE ORBITER THERMAL SYSTEM SPECIFICATION			
EFFECTIVITY: <input type="checkbox"/> ALL <input checked="" type="checkbox"/> ACS <input checked="" type="checkbox"/> ACS ANALYSIS <input checked="" type="checkbox"/> C&DH <input checked="" type="checkbox"/> COMMUNICATIONS <input type="checkbox"/> ELECT. HARNESS <input checked="" type="checkbox"/> FLT DYNAMICS <input checked="" type="checkbox"/> GN&C <input checked="" type="checkbox"/> I&T <input checked="" type="checkbox"/> LAUNCH VEHICLE <input checked="" type="checkbox"/> MECHANICAL <input checked="" type="checkbox"/> MECH. ANALYSIS <input type="checkbox"/> EGSE <input type="checkbox"/> MGSE <input checked="" type="checkbox"/> SPACECRAFT <input checked="" type="checkbox"/> THERMAL <input type="checkbox"/> MASS <input checked="" type="checkbox"/> PAYLOAD/INSTR. <input checked="" type="checkbox"/> POWER <input checked="" type="checkbox"/> PROPULSION <input checked="" type="checkbox"/> SOFTWARE <input type="checkbox"/> FLIGHT OPS <input type="checkbox"/> WGHT <input type="checkbox"/> GND SYS <input type="checkbox"/> OTHER _____			
<b>Change Class</b>	<b>Criticality</b>	COST? <input checked="" type="checkbox"/> NO <input type="checkbox"/> YES <b>If yes, select one basis for estimate:</b>	
<input checked="" type="checkbox"/> Class I <input type="checkbox"/> Class II	<input type="checkbox"/> Emergency <input checked="" type="checkbox"/> Urgent <input type="checkbox"/> Routine	<input type="checkbox"/> In-House	<input type="checkbox"/> Actuals
		<input type="checkbox"/> ROM	<input type="checkbox"/> Historical Averages
		<input type="checkbox"/> Other**	
** If "Other" is chosen for the Basis of Estimate, please explain in Proposed Solution box below:			
<b>PROBLEM:</b>  Document needs to be revised to include updates (i.e., temperature changes).			
<b>PROPOSED SOLUTION:</b>  Recommend approval/release of the attached redline version as Revision A of the document.			
TYPE OF CHANGE: <input type="checkbox"/> Schedule <input type="checkbox"/> Interface <input checked="" type="checkbox"/> Document <input type="checkbox"/> Waiver <input type="checkbox"/> Deviation <input type="checkbox"/> Contract <input type="checkbox"/> Other _____			

## LUNAR RECONNAISSANCE ORBITER PROJECT CONFIGURATION CHANGE REQUEST

<b>CCR: 431-CCR-000105</b>	<b>DATE INITIATED:</b> 2/2/2006	<b>CCR REV.:</b>	<b>CCR REV DATE:</b> _____
<b>CCB SECRETARY: DEB YODER</b>	<b>PROPRIETARY?</b> <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	<b>ITAR SENSITIVE?</b> <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	<b>CCR DUE DATE:</b> 2/14/2006
<b>BOARD ACTION:</b> <input type="checkbox"/> APPROVED <input type="checkbox"/> APPROVED WITH CHANGE <input type="checkbox"/> DISAPPROVED <input type="checkbox"/> WITHDRAWN <input type="checkbox"/> DEFERRED			
<b>Comments</b>			
<b>CCB APPROVAL LEVEL REQUIRED [Check appropriate box(es)]:</b>			
<input type="checkbox"/>	LEVEL 1 NASA HQ	<b>Signature:</b>	<b>Date:</b>
<input type="checkbox"/>	LEVEL 2 RLEP	<b>Signature:</b>	<b>Date:</b>
<input checked="" type="checkbox"/>	LEVEL 3 LRO	<b>Signature:</b>	<b>Date:</b>

October 3, 2005, Rev A

431-SPEC-000091

Revision -A

~~Effective Date: November 29, 2005~~

~~Expiration Date: November 29, 2010~~

# DRAFT

## Lunar Reconnaissance Orbiter

### Thermal System Specification

~~August 18, 2005~~ February 2, 2006



Goddard Space Flight Center  
Greenbelt, Maryland

National Aeronautics and  
Space Administration

CHECK WITH ~~RLEP-LRO~~ DATABASE AT:  
<https://lunarngin.gsfc.nasa.gov>  
TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

## CM FOREWORD

This document is a Lunar Reconnaissance Orbiter (LRO) Project Configuration Management (CM)-controlled document. Changes to this document require prior approval of the applicable Configuration Control Board (CCB) Chairperson or designee. Proposed changes shall be submitted to the LRO Project CM Office (CMO), along with supportive material justifying the proposed change. Changes to this document will be made by complete revision.

Questions or comments concerning this document should be addressed to:

LRO Project Configuration Management Office  
Mail Stop 431  
Goddard Space Flight Center  
Greenbelt, Maryland 20771

**Signature Page**

***Prepared by:***

\_\_\_\_\_  
Charles Baker  
LRO Thermal Systems Lead  
GSFC/NASA, Code 545

\_\_\_\_\_  
Date

***Reviewed by:***

\_\_\_\_\_  
Mike Pryzby  
LRO Mission Systems Engineer  
Swales/Code 543

\_\_\_\_\_  
Date

***Approved by:***

\_\_\_\_\_  
Craig Tooley  
LRO Project Manager  
GSFC/NASA, Code 431

\_\_\_\_\_  
Date

**LUNAR RECONNAISSANCE ORBITER PROJECT**

**DOCUMENT CHANGE RECORD**

Sheet: 1 of 1

REV LEVEL	DESCRIPTION OF CHANGE	APPROVED BY	DATE APPROVED
Rev -	Released per 431-CCR-000022	C. Tooley	11/17/2005

CHECK WITH ~~RLEP-LRO~~ DATABASE AT:  
<https://lunarngin.gsfc.nasa.gov>  
 TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

## List of TBDs/TBRs

Item No.	Location	Summary	Ind./Org.	Due Date
1	Section 1.4.1, 2.2, and 3.3	Provide document numbers to replace TBDs for Specific Thermal Hardware Specs and General Thermal Hardware Specs	C. Baker/ GSCF	8/1/2006
2	Section 1.4.2	Provide document number to replace TBD for LRO Thermal Balance/Thermal Vacuum Test Plan	C. Baker/ GSCF	8/1/2006
3	Table 2-1	<del>Update Structure Temperatures</del>	<del>C. Baker/ GSCF</del>	<del>3/15/2006</del>
4	<del>Section 2.7</del>	<del>Number of Internal Telemetry Points on various components are TBR</del>	<del>Rick Kinder/ OSC</del>	<del>2/1/2006</del>
5	Section 3.3.2, Table 3-1	Need to provide TBRs and TBDs to descriptions of Mission modes when details of Mission Design Concept are completed	Riek Saylor/ HTSI	2/1/2006
6	Section 3.3.3, Table 3-2	Provide Orbit Average Power of Active controlled heater circuits to replace TBDs	C. Baker/ GSCF	8/1/2006
7	Section 3.3.6	Operational versus survival heaters on GYRO located on Essential Heater Bus is TBR.	C. Baker/ GSCF	8/1/2006
8	Section 3.4	<del>Spacecraft Allocations per heater circuit peak and Driving Beta Angles are TBDs</del>	<del>C. Baker/ GSCF</del>	<del>8/1/2006</del>
9	Section 5.2	Thermal Coatings Table has TBDs	W. Peters/ GSCF	12/1/2006

CHECK WITH ~~RLEP-LRO~~ DATABASE AT:<https://lunarngin.gsfc.nasa.gov>

TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

## TABLE OF CONTENTS

		<u>Page</u>
<b>1.0</b>	<b>Scope.....</b>	<b>1-1</b>
1.1	General.....	1-1
1.2	Purpose.....	1-1
1.3	Responsibility .....	1-1
1.4	Documents .....	1-1
	1.4.1 Applicable Documents.....	1-1
	1.4.2 Reference Documents .....	1-2
<b>2.0</b>	<b>Temperture Requirements.....</b>	<b>2-1</b>
2.1	Types of Temperature Limits.....	2-1
2.2	Location of Flight Telemetry .....	2-1
2.3	Flight Interface Design Temperature Limits.....	2-2
2.4	Temporal Gradient Requirements.....	2-2
2.5	Spatial Gradient Requirements .....	2-4
2.6	Turn On Temperature and Survival .....	2-6
2.7	Allocation of Spacecraft Monitored Temperature Sensors.....	2-6
<b>3.0</b>	<b>Thermal Power.....</b>	<b>3-1</b>
3.1	General heater circuit Requirements.....	3-1
3.2	Thermal Dissipated Power Per Mission Mode .....	3-1
3.3	Spacecraft Controlled Thermal Control Heater Power.....	3-1
	3.3.1 Instrument Operation Heater Power Description.....	3-1
	3.3.2 Spacecraft Operational Thermal Control Heat Power Description.....	3-3
	3.3.3 Tight Bandwidth Command and Data Handling and Software Controlled Heater.....	3-3
	3.3.4 Propulsion System Heaters Primary and Redundant Description.....	3-3
	3.3.5 Deployment Heaters Description.....	3-4
	3.3.6 Essential Heaters Prime and Redundant Description.....	3-4
	3.3.7 Instrument Survival Heaters Description.....	3-4
3.4	Spacecraft Heater Allocation .....	3-4
3.5	Instrument Heater Allocation (Wired to Spacecraft Switch).....	3-4
3.6	Instrument Heater Allocation (Controlled by Components/ Instruments).....	3-5
<b>4.0</b>	<b>Multi-Layer Insulation Blankets .....</b>	<b>4-1</b>
4.1	Outer Blanket Coating .....	4-1
4.2	Multi-Layer Insulation Blanket Grounding .....	4-1
4.3	Multi-Layer Insulation Blanket Documentation.....	4-1
4.4	Attachment of Multi-Layer Insulation Blankets.....	4-1
<b>5.0</b>	<b>Thermal Analysis .....</b>	<b>5-1</b>
5.1	Environmental Conditions .....	5-1
	5.1.1 Thermal Conditions .....	5-1
	5.1.2 Payload Fairing Ascent Pressure Profile.....	5-1



**TABLE OF CONTENTS (CONTINUED)**

	<u>Page</u>
5.2 Thermal Coatings.....	5-2
5.3 Hot and Cold Bias of Power .....	5-3
5.4 Mission Modes.....	5-4
5.5 Thermal Model Margin.....	5-4
5.6 Thermal Modeling Scope.....	5-4
5.7 Thermal Analysis Documentation .....	5-4
<b>6.0 Component and Orbiter Integration and Test.....</b>	<b>6-1</b>
6.1 Component Thermal Cycling Requirement .....	6-1
6.2 Model Documentation .....	6-1
6.3 Component Thermal Test Model.....	6-1
6.4 Component Thermal Test Documentation.....	6-1
6.5 Thermal Model Correlation .....	6-1
6.6 Reduced Model .....	6-2
6.7 In-Air Thermal Control.....	6-2
6.8 Orbiter Thermal Vacuum/Balance Levelness and Orientation Requirements.....	6-2
6.9 Lunar Reconnaissance Orbiter Coordinate System .....	6-2
6.10 Test Heaters .....	6-2
6.11 Test Sensors .....	6-3
<b>Appendix A. Abbreviations and Acronyms.....</b>	<b>A-1</b>

**LIST OF FIGURES**

<u>Figure</u>	<u>Page</u>
Figure 5-1. Delta II-Like Fairing Pressure.....	5-2
Figure 6-1. LRO Coordinate System Definition.....	6-3

**LIST OF TABLES**

<u>Table</u>	<u>Page</u>
Table 2-1. Spacecraft Temperature Range.....	<b>Error! Bookmark not defined.</b>
Table 2-2. Temporal Gradient Requirements .....	<b>Error! Bookmark not defined.</b>
Table 2-3. Spatial Gradient Requirements.....	2-5
Table 2-4. Thermistor Allocation .....	2-6
Table 3-1. Component Thermal Power Dissipations.....	3-2
Table 3-2. Five Tight Control Heaters Powered by C&DH .....	3-3

**LIST OF TABLES (CONTINUED)**

<u>Table</u>	<u>Page</u>
Table 3-3. Spacecraft Control Heater Power Allocations.....	<b>Error! Bookmark not defined.</b>
Table 3-4. Instrument Control Heater Power Allocations on the SC Instrument Operational Bus .....	3-5
Table 3-5. Instrument Control Heater Power Allocations .....	3-5
Table 5-1. LRO Solar Constant and Albedo Factor.....	5-1
Table 5-2. LRO Lunar Infrared.....	5-1
Table 5-3. LRO Thermal Coatings .....	5-2

## **1.0 SCOPE**

### **1.1 GENERAL**

This General Subsystem Thermal Specification defines and controls the top level thermal requirements for all components on the Lunar Reconnaissance Orbiter (LRO) spacecraft (SC). The specification places requirements on both sides of the SC-to-component interface to insure mission thermal safety. More details are controlled at lower level specifications such as the Thermal Interface Control Documents (ICD) specified in Section 4.1. This document outlines:

- a. Temperature Requirements
- b. Bounding Environmental Parameters
- c. Thermal Test Requirements
- d. Thermal Analysis Requirements (bounding inputs and required outputs)
- e. Thermal Report Requirements
- f. Component Thermal Hardware Drawings and Diagrams Requirements
- g. Instrument Allocated Operational and Survival Heater Power

### **1.2 PURPOSE**

The purpose of this specification is to clearly define what is expected of every temperature sensitive component to be flown on LRO and the LRO thermal control system to satisfy that the component is safe to fly on LRO. This document is focused on the thermal interface to the SC but also requires that analysis be performed to show thermal safety throughout the powered component during all mission modes.

### **1.3 RESPONSIBILITY**

The Goddard Space Flight Center (GSFC) has the final responsibility for the LRO mission, the Orbiter, its subsystems, and any requirements specifically assigned to LRO in this document.

LRO systems engineering and project management have the ultimate authority to specify thermal requirements. This document shall be the vehicle by which changing thermal requirements are tracked.

### **1.4 DOCUMENTS**

#### **1.4.1 Applicable Documents**

The following documents form a part of this Specification to the extent specified herein:

431-OPS-000042	Lunar Reconnaissance Orbiter Mission Concept of Operations
431-RQMT-000092	Lunar Reconnaissance Orbiter Thermal Math Model Requirements
431-SPEC-000008	Lunar Reconnaissance Orbiter Electrical Systems Specification
431-SPEC-000112	Lunar Reconnaissance Orbiter Technical Resource Allocations Specification

- 431-SPEC-**TBD** Lunar Reconnaissance Orbiter General Thermal Hardware Specification
- 431-SPEC-**TBD** Lunar Reconnaissance Orbiter Project <Specific> Thermal Hardware Specification

#### **1.4.2 Reference Documents**

- 431-ICD-000114 Lunar Reconnaissance Orbiter Camera Thermal Interface Control Document
- 431-ICD-000115 Lyman-Alpha Mapping Project Thermal Interface Control Document
- 431-ICD-000116 Diviner Lunar Radiometer Experiment Thermal Interface Control Document
- 431-ICD-000117 Lunar Orbiter Laser Altimeter Thermal Interface Control Document
- 431-ICD-000118 Cosmic Ray Telescope for Effects of Radiation Thermal Interface Control Document
- 431-ICD-000119 Lunar Exploration Neutron Detector Thermal Interface Control Document
- 431-PLAN-**TBD** Lunar Reconnaissance Orbiter Project Thermal Balance/Thermal Vacuum Test Plan
- 431-SPEC-000012 Lunar Reconnaissance Orbiter Mechanical Systems Specification
- GSFC-STD-7000 General Environmental Verification Standards (GEVS) for Flight Programs and Projects
- MIL-R-39009 General Specification for Resistors, Fixed, Wire-Wound (Power Type, Chassis Mounted)
- NASA GSFC S311-641 Switch, Thermostatic, Bimetallic, SPST, Narrow Differential, Hermetic
- NASA GSFC S311-P-079 Procurement Specification for Thermofoil Heaters
- 431-ICD-000159 Mini-RF to Spacecraft Thermal Interface Control Document

## 2.0 TEMPERATURE REQUIREMENTS

These requirements apply to all flight powered components. To clarify the language used, a brief discussion of temperature limits vocabulary will explain the different types of limits.

### 2.1 TYPES OF TEMPERATURE LIMITS

There are three sets of temperature limits associated with critical locations and the SC-to-instrument thermal interface locations, defined as follows:

- a. Survival Limits: The minimum and maximum non-operating temperatures that may be experienced without inflicting damage or permanent performance degradation. Components must demonstrate that they can operate properly in thermal vacuum after exposure to cold survival limits. Survival limits must be at least as wide as qualification temperature limits.
- b. Qualification Temperature Limits: The minimum and maximum over which the responsible hardware manager has proven the component works thru qualification. The Qualification limits are 10 C outside of the Flight Limits. Acceptance Limits are 5 C outside of the Flight Limits. Any component that may be considered for Acceptance testing must present the case to the LRO Thermal Systems Lead that the same design component has been qualified in a relevant environment for LRO. The responsible hardware manager shall induce the qualification temperature limits in thermal vacuum testing prior to delivery to verify that the hardware can operate and survive over the entire specified temperature range.
- c. Flight Operational Limits: The flight operational limits must be at least 10°C inside the qualification limits, except for actively controlled components. The flight operational limits are treated as an “allocation” in the sense that the responsible hardware manager commits to not exceed them by design.

### 2.2 LOCATION OF FLIGHT TELEMETRY

There shall be temperature limits on all flight telemetry points during all phases of monitoring. However, it is the responsibility of the Orbiter thermal subsystem to only manage telemetry and limits at thermal interfaces that are specified in ICDs or subordinate specifications. These locations are designated by applicable component mechanical interface drawings provided by the responsible hardware manager. This location may be where the component attaches to a SC module deck or on the outside of a mutually agreed up location of the component that shall be clearly defined. Inside box/ component locations are acceptable if installed by component development team and reflected in the appropriate electrical ICD. Within the component itself, there is likely to be other telemetry which may or may not be monitored by the SC, which shall be the responsibility of the responsible hardware manager. It is the responsibility of the hardware manager to analytically or via test determine that all other temperature limits within the component are met as long as the system thermal interface is maintained within limits (qualification or

acceptance). Locations of the temperature limits as defined by the use of telemetry shall be defined by diagram or figure provide in the end item data package (EIDP) prior to delivery of the component to the orbiter assembly in an as-built location. All orbiter-controlled telemetry shall be defined in the Lunar Reconnaissance Orbiter Thermal Hardware Specification (431-SPEC-TBD) document or component specific documentation.

### 2.3 FLIGHT INTERFACE DESIGN TEMPERATURE LIMITS

Table 2-1 below lists the design temperature limits at the SC thermal interface.

**Table 2-1a. Spacecraft Interface Temperature Range**

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)	
		Op I/F Limit	Surv I/F Limit
Power	Power Subsystem Electronics S/C I/F at PSE	-10 to +40	-20 to +50
	S/C I/F at Battery	+10 to +30	+0 to +40
Attitude Control System (ACS)	S/C I/F at Star Trackers (Top of Wedge)	-30 to +50	-40 to +60
	S/C I/F at Inertial Measurement Unit	-30 to +65	-35 to +75
	S/C I/F at Reaction Wheels	0 to +50	-30 to +60
	S/C I/F at Coarse Sun Sensors	-140 to +135	-140 to +145
Propulsion and Deployables Electronics (PDE)	S/C I/F at PDE	-10 to +40	-20 to +50
C&DH	S/C I/F at C&DH	-10 to +40	-20 to +50
S Comm	S/C I/F at S-band components	-10 to +50	-20 to +60
Ka Comm	S/C I/F at Ka Baseband Modulator	-10 to +50	-20 to +60
	S/C I/F at Ka TWT	-10 to +70	-20 to +80
	EPC	-10 to +50	-20 to +60
Cosmic Ray Telescope of the Effects of Radiation (CRaTER)	S/C at I/F to CRaTER	-30 to +25	-40 to +35
Diviner	S/C at I/F to Diviner Instr	-20 to +45	-35 to +55
	S/C at I/F to remote electronics box	-10 to +45	-20 to +55

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)	
		Op I/F Limit	Surv I/F Limit
<b>Lyman-Alpha Mapping Project (LAMP)</b>	S/C I/F at base of LAMP's feet	-30 to +30	-40 to +40
<b>Lunar Exploration Neutron Detector (LEND)</b>	S/C at I/F to LEND	-20 to +40	-30 to +50
<b>Lunar Orbiter Laser Altimeter (LOLA)</b>	S/C at I/F to Optics Package	-30 to +30	-40 to +40
	S/C at I/F to Instrument Electronics	-30 to +40	-40 to +50
<b>Lunar Reconnaissance Orbiter Camera (LROC)</b>	S/C at base of NAC	-30 to +30	-40 to +40
	S/C I/F at base of WAC	-30 to +30	-40 to +40
	S/C I/F at base of SCS	-30 to +30	-40 to +40
<b>Mini RF</b>	S/C I/F at base of antennae's feet	-50 to +50	-60 to +60
	S/C I/F at base of electronics feet	-30 to +50	-40 to +60
<b>S/A Gimbal I/F</b>	Gimbal I/F to Solar Array	-10 to +50	-20 to +60
<b>Hi-Gain Gimbal I/F</b>	Gimbal I/F to Solar Array	-10 to +50	-20 to +60

Table 2-1b. Component Design Temperature Range

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)	
		Operational	Survival
<b>Mechanical</b>	Structure Propulsion Module	-50 to +70	-60 to +80
	Structure -Avionics Module	-50 to +50	-60 to +60
	Structure -Avionics to Propulsion	-50 to +50	-60 to +60
	Structure. Instrument Module	-40 to +50	-50 to +60
<b>Mechanisms</b>	High Gain Antenna (HGA) Gimbals	-10 to +50	-20 to +60
	HGA Boom	-75 to +75	-85 to +85
	HGA Release and Deploy	-10 to +50	-20 to +60
	Solar Array (S/A) Gimbals	-10 to +50	-20 to +60
	S/A Boom	-10 to +50	-20 to +60

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)	
		Operational	Survival
	S/A Release and Deploy	-10 to +50	-20 to +60
<b>Propulsion System (wetted components only)</b>	Hydrazine Tank 1	+10 to +40	N/A
	Pressure Tanks	+0 to +50	N/A
	90N Thrusters	N/A	N/A
	22N Thrusters	N/A	N/A
	High Press Transducers	+10 to +40	N/A
	Low Press Transducer	+10 to +40	N/A
	Gas Latch Valve	+10 to +40	N/A
	Liquid Latch Valve	+10 to +40	N/A
	Fill and Drain	+10 to +40	N/A
	Gas System Filters	+0 to +50	N/A
	Liquid Filters	+10 to +40	N/A
	Pressure Regulators	+0 to +50	N/A
	Plumbing Lines	+10 to +40	N/A
NC Pyro Valves	-40 to +40	-60 to +50	
<b>K-Band Comm</b>	HGA	-140 to +145	-140 to +145
	Wave Guide	-50 to +50	-60 to +60
<b>S-Band Comm</b>	TT&C Omni Antenna	-120 to +80	-130 to +90
<b>Power</b>	Solar Array	-125 to +135	-160 to +145

## 2.4 TEMPORAL GRADIENT REQUIREMENTS

Table 2-2 below lists the temporal gradient requirements. Temporal gradient rates shall be evaluated over 6 minute average time periods minimum.

**Table 2-2. Temporal Gradient Requirements**

SUBSYSTEM	COMPONENT	TEMPORAL GRADIENT (°C/min)
<b>CRaTER</b>	S/C I/F to the Instrument	None
<b>Diviner</b>	Remote Electronics Box Baseplate	1.0
	S/C I/F to Diviner Instrument	None
<b>LAMP</b>	S/C I/F to LAMP Instrument	None



SUBSYSTEM	COMPONENT	TEMPORAL GRADIENT (°C/min)
LEND	Instrument Baseplate	2.
LOLA	Optics Package	None
	Instrument Electronics	None
LROC	NAC (2)	None
	WAC	None
	Instrument Electronics	None
Mini-RF	Antennae	None
	Electronics Box	None

## 2.5 SPATIAL GRADIENT REQUIREMENTS

Table 2-3 below lists the spatial gradient requirements between mounting feet.

**Table 2-2. Spatial Gradient Requirements**

SUBSYSTEM	COMPONENT	SPATIAL GRADIENT Between Mounting Feet (°C)
CRaTER	S/C I/F to the Instrument	None
Diviner	S/C I/F to Remote Electronics Box	None
	S/C I/F to Diviner Instrument	None
LAMP	S/C I/F to LAMP Instrument	None
LEND	Instrument Pkg.#4	None
LOLA	Optics Package	None
	Instrument Electronics	None
LROC	NAC (2)	None
	WAC	None
	Instrument Electronics	None
ACS	Star Cameras	None
COMM	Hi-Gain Gimbals	None
Mini-RF	Antennae	None
	Electronics Box	None

## 2.6 TURN ON TEMPERATURE AND SURVIVAL

When powered “OFF”, each component shall be capable of surviving indefinitely when its temperatures are within the qualification survival limits without damage or permanent performance degradation.

All components shall also survive indefinitely, without damage or permanent performance degradation, if powered “ON” anywhere from the minimum survival temperature to 10°C above the maximum operating temperature.

For components that are conductively coupled to the SC, when powered “OFF”, the SC Thermal Control System shall maintain the instruments within the design survival temperature limits. If necessary, the SC will use survival heating as described in Section 3.2.6 to maintain the low limit.

## 2.7 ALLOCATION OF SPACECRAFT MONITORED TEMPERATURE SENSORS

Table 2-4 specifies the number of SC monitored temperature sensors allocated to each component. The telemetry types listed only apply to the column in the table labeled “Number of Telemetry Points”. The ‘Internal Box Telemetry’ sensors can be alternative telemetry types since they may be read by alternative avionics. The current baseline for temperature sensors is 2.252 ohms S311P18-02-A-7R6 or Platinum Resistance Thermistor (PRT) (118MF2000AC, 2000 ohms @ 0°C) as specified by the LRO Thermal Systems Lead. The thermistor/PRT shall be capable of being read over the all temperature ranges specified. The sensors shall be accurate within 0.5°C from -45 to +75°C. The thermistor electrical interface shall be per the relevant electrical ICD and that the physical placement of each thermistor is per the relevant thermal ICD.

**Table 2-3. Thermistor Allocation**

Subsystem	Details	Thermistors	PRTs
<b>Mechanical</b>		36	9
Comp. Propulsion Module	Rationale: Need to understand if Cat Beds are working and temperature of HP and LP modules. Need to know driving sources of propulsion Module if problem arises		
	Hi-Temperature Cat Bed PRTs		8
	L/V I/F at S/C I/F		1
	Central Cylinder at tank I/F	2	

	Central Cylinder at tank I/F	2	
	Pressurant tank I/F	2	
	HPCM	1	
	LPCM	1	
	Outer Structure of Prop Module	2	
Comp. Spacecraft Bus Module	Rationale: Need to understand Radiator and central structure		
	Central Cylinder	2	
	Radiators	4	
Comp. Instrument Module	Rationale: Need to do in-flight STOP if pointing problem.		
	Interfaces with Structure +Y	2	
	Interfaces with Structure -Y	2	
	Roughly a thermistor per ft <sup>2</sup>	10	
	+/- Y IM wings	6	
<b>Mechanisms</b>		<b>26</b>	
HGA Gimbals			In HG&SA Cntrl Box
HGA Boom			
HGA Release & Deploy			
	Deployment Hinge	2	
	Dampers	2	
	Release point	2	
S/A Gimbals			In HG&SA Cntrl Box
S/A Boom			
S/A Release & Deploy			
	Deployment Hinge (3)	6	
	Dampers (3)	6	
	Release point (3)	6	
S/A HGA Control Electronics			
	Box Reference Point #1	1	
	Box Reference Point #2	1	
<b>Thermal</b>		<b>49</b>	
Thermal Control Heaters (Redundant)	Rationale: If thermistor fails, circuit fails	10 (active control)	
Fuel Tank Heaters (2 smaller tanks)	Rationale: Need be able to turn off a heater circuit if problematic. Fuel temperatures must be controlled.	8	
Fuel Line Heaters	"	10	
20# Valve heaters	"	4	
5# Valve Heaters	"	8	

S/A Gimbal thermal control at each heater	Rationale: Monitor Each Heater Circuit	2	
High Gain Gimbal thermal control at each heater	Rationale: Monitor Each Heater Circuit	2	
Survival Heater Location all on instruments	Rationale: Monitor Heater Circuit to ensure survival heater		
	LEND	1	
	CRaTER	1	
	LAMP	1	
	Mini-RF (2 pieces)	2	
	Note: bench survival heater telemetry are in IM mech		
<b>Power</b>		<b>5</b>	
	PSE	1	0
	Battery	2	
	S/A Cells/Cover Glass		
	S/A Substrate		4
<b>ACS</b>		<b>8</b>	
<b>S/C I/F and Reference pt</b>	PDE	2	
<b>S/C I/F assumes internal telemetry elsewhere</b>	Star Trackers	1	
<b>S/C I/F assumes internal telemetry elsewhere</b>	Inertial Measurement Unit	1	
<b>At Reference Point only near S/C I/F</b>	Reaction Wheels	4	
	Coarse Sun Sensors		
<b>Propulsion</b>			
<b>These telemetry points are contained under thermal and Mechanical Structure</b>			
	Hydrazine Tank		
	Pressure Tanks		
	20# Thrusters		
	20# Cat Bed		
	5# Thrusters		
	5# Cat Bed		
	Pressure Transducers		
	HP Latch Valves		
	LP Latch Valves (1/4)		
	Fill and Drain		

	Gas System Filters		
	Propellant Filters		
	Pressure Regulators		
	Plumbing Lines		
	NC Pyro Valves		
<b>C&amp;DH</b>		<b>6</b>	
<b>DDA</b>	Disk Drive 1	1	
	Disk Drive 2	1	
	Survival Heaters on Case	1	
<b>Oscillator</b>	Survival Heater	2	
<b>C&amp;DH Box</b>	Survival Heater	1	
	Reference temperature assumed to be taken care of by C&DH		
<b>S Comm</b>		<b>6</b>	
<b>TT&amp;C</b>	TT&C XPDR Stack (xmit)	1	
	TT&C XPDR Stack (Rec)	1	
	USB Diplexer		
	USB RF Switch		
	USB Coupler		
	USB Hybrid		
	USB Terminator		
	TT&C Omni Antenna	4	
	USB Isolator		
<b>Relay</b>	TT&C Coax Cables		
	Relay Transciever		
	ISM Diplexer		
	ISM RF Switch		
	ISM Hybrid		
	ISM Coupler		
	ISM Terminator		
<b>Ka Comm</b>		<b>4</b>	<b>3</b>
	Ka Baseband Modulator		
	Ka EPC	2	
	Ka TWTA	2	
	Ka Bandreject Filter		
	WG-34 Ka Band Waveguide		
	High Gain Antenna		3
<b>Electrical</b>			
	Harness		
	<b>Total Instruments</b>	<b>22</b>	
<b>CRaTER</b>	<b>INST #1</b>	<b>1</b>	
	Telescope	1	

<b>Diviner</b>		<b>5</b>	
	OBA	1	
	Az Actuator	1	
	Elev Actuator	1	
	DREB	1	
	Yoke	1	
<b>LAMP</b>	<b>INST #3</b>	<b>1</b>	
	LAMP Reference Point	1	
<b>LEND</b>	<b>INST #4</b>	<b>2</b>	
	LEND Elec	1	
	LEND Detector	1	
<b>LOLA</b>	<b>INST #5</b>	<b>3</b>	
	PCA I/F	1	
	DU I/F	1	
	LOLA Optical Bench	1	
<b>LROC</b>	<b>INST #6</b>	<b>8</b>	
	TBD	3	
	TBD	5	
<b>Mini-RF</b>	<b>Tech Development</b>	<b>2</b>	
	S/C I/F to Antennae	1	
	S/C I/F to Electronics	1	
	<b>S/C SUBTOTAL</b>	<b>138.00</b>	<b>12</b>
	<b>INSTRUMENTS TSUBTOTAL</b>	<b>22.00</b>	
	<b>TOTAL</b>	<b>160</b>	<b>12</b>

### **3.0 THERMAL POWER**

#### **3.1 GENERAL HEATER CIRCUIT REQUIREMENTS**

Sizing of operational and survival heater capacity shall be based on 70% duty cycle at 24 volts (V) bus voltage and cold case thermal conditions. Heater elements must be capable of operating over the voltage range of  $28 \pm 7V$ .

Each component shall provide space for mounting thermostats, heaters and temperature sensors. Heaters, if Kapton film heaters, shall comply with NASA GSFC S311-P-079. Heaters, if Vishay Dale Ohm, shall comply with Military/Established Reliability, MIL-R-39009 Qualified, Type RER, R Level, Aluminum Housed, and be Standard (ERH). Mechanical Thermostats, if used, shall comply with NASA GSFC S311-641.

Watt densities of the operational and survival heaters shall be appropriate for the type of heater and bonding method. Watt densities (calculated at the maximum voltage) above 0.16 Watts per centimeters squared ( $W/cm^2$ ) (1.0 Watts per inch squared [ $W/in^2$ ]) shall be approved by the GSFC LRO Thermal Engineer Lead and may require (if a Kapton heater) bonding with Stycast 2850FT and aluminum over-taping up to  $1.24 W/cm^2$  ( $8.0 W/in^2$ ).

#### **3.2 THERMAL DISSIPATED POWER PER MISSION MODE**

Thermal dissipative power is different from electrical power allocation due to the need to identify the location where the electrical power is dissipated. The purpose for this section is to handshake with the responsible hardware manager what inputs are used in the overall thermal model during which mission mode. Embedded into thermal dissipative power is the need to analyze the worst case orbit average power both high and low even if it is just for one orbit. Table 3-1 shows power dissipations by component without margin. It also details all mission modes that the components shall experience including pointing and SC configuration.

#### **3.3 SPACECRAFT CONTROLLED THERMAL CONTROL HEATER POWER**

The SC shall control several heater power circuits. These heater power circuit sizes and locations are detailed in the Lunar Reconnaissance Orbiter Thermal Hardware Specification (431-SPEC-~~TBD~~) document. This specification provides details with respect to orbit average heater dissipation and peak power dissipation.

##### **3.3.1 Instrument Operational Heater Power Description**

This switch is intended to service operational heaters in the instrument module. Nominally, the heaters will be located at the component. The sizing of the heaters will be designed such that all components are maintained thermostatically at the low end of the operational temperature range regardless of the actual power that the component is dissipating during different regular operational modes. In the cold case, this heater power is necessary to offset the losses from the instrument to the environment and the variation in power based on different operational modes.

Table 3-1. Component Thermal Power Dissipations and Thermal Mission Modes

Table with columns for component names and 32 mission modes (3.0 to 8.0). Rows include various subsystems like S/C Pointing, Thermal Cooling Method, Time Duration of mode, Leveling Requirement, Deployment Hrs, Thermal Dissipation (W), and Total Thermal Dissipation. The table is highly detailed with numerical values for power dissipation and mission mode availability (Y/N).

CHECK WITH [RLEP-LRO.DATABASE AT:](http://rlep-lro.database.at)  
<https://lunarngin.gsfc.nasa.gov>  
TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.



In the hotter Beta angles, this heater power will be reduced and eliminated as the environment warms up. When the instruments are not operating, this heater switch will be switched off to preserve power such as during the lunar eclipse.

### **3.3.2 Spacecraft Operational Thermal Control Heat Power Description**

This switch is intended to service SC components regardless of where they are located (propulsion module, Avionics deck, or instrument module). This switch feeds the separately wired thermostatically controlled operational heaters. These heaters will also provide some heater power to components during cold operational periods that prevent components from exceeding their cold operational temperature due to losses from those components to the cold environment. These SC components will be ones that may be switched off during lunar eclipse or safe hold modes of operation. This heater circuit may be switched off during lower power modes such as lunar eclipse or safe hold and therefore should only service components that either needs tighter stability during certain fully operational modes or components that are switched off automatically during lunar eclipse or safe hold conditions. Examples of these components are the Star Trackers operational, Hi-Gain gimbal operational, and Traveling Wave Tube Amplifier (TWTA) operational heaters.

### **3.3.3 Tight Bandwidth Command and Data Handling and Software Controlled Heater**

An additional five tight temperature control circuits have been allocated per Table 3-2. This allows tailoring of these five thermal control points to fine tune thermal control. The intention of these heater circuits is to resolve thermal control/stability issues that arise later in the program.

**Table 3-2. Five Tight Control Heaters Powered by C&DH**

<b>Heater # / Max Amp</b>	<b>COMPONENT</b>	<b>Orbit Avg Power at 24 V/Peak Power at 35 V</b>
<b>1/5 amp</b>	<b>Isothermal Bench</b>	51
<b>2/2 amp</b>	<b>AP VCHP#1</b>	10
<b>3/2 amp</b>	<b>AP VCHP#1</b>	10
<b>4/2 amp</b>	<b>AP VCHP#1</b>	10
<b>5/2 amp</b>	<b>LEND Radiator</b>	20

### **3.3.4 Propulsion System Heaters Primary and Redundant Description**

This switch is intended to service the propulsion system heaters and is redundant. The heaters will be located on the thruster valve heaters, propulsion lines, propulsion tanks, and the propulsion pressurization tank. These heaters shall be enabled during all mission modes as they are designed to prevent the Hydrazine from freezing.

### **3.3.5 Deployment Heaters Description**

This switch controls operational thermostatically controlled heaters at the deployment mechanisms and hinges to ensure deployment within the operational range. These heaters will be switched off after deployment to preserve heater power.

### **3.3.6 Essential Heater Description**

These unswitched services are designed to prevent components that are always enabled (essential) during all mission modes from exceeding the lower operational temperature limit and to prevent SC components that may be switched off from exceeding their lower survival temperature limit. The two thermostatically controlled heater circuits shall be offset in setpoint so that their operation can be verified separately during observatory thermal vacuum testing and to prevent the higher peak which would result if the two redundant thermostats sets were to possible snap closed at the same time. Examples of heaters on this circuit would be: C&DH operational heaters, battery operational heaters, S-Band operational heater, and Ka band transmitter survival heaters. Survival heaters for the Gyro (**TBR**) will be on this circuit. Also included are survival heater for avionics that require them in non-operational modes.

### **3.3.7 Instrument Survival Heaters Description**

This service will primarily service the instruments and instrument module to maintain all the instruments within their cold survival temperature. These heaters shall be wired out from the common service to two separate heater services located on the instruments. It is expected that these services will be thermostatically controlled and may be located on the instruments themselves. This bus also include survival heater for the de-coupled optical bench and LEND and CRaTER radiators heater control.

## **3.4 SPACECRAFT HEATER ALLOCATION**

The heater allocation is per the Technical Resource Allocations Specification 431-SPEC-000112.

## **3.5 INSTRUMENT HEATER ALLOCATION (WIRED TO SPACECRAFT SWITCH)**

The instrument heater power allocation on the SC Instrument Operational bus is outlined in Table 3-4 and described in Section 3.2.1. The power shown is at 24V and is the size of the heater with the General Environmental Verification Standards (GEVS) margin 70% duty cycle (i.e., the powers below are an orbit average with a 70% duty cycle not what the power would be if the heaters were at 100% duty cycle because by design they will not exceed 70%). All services shall be thermostatically controlled at the instrument. The SC is providing no active control. Heaters shall be NASA GSFC S311-079 Kapton film heaters or Vishay Dale Ohm heaters (MIL-R-39009 Qualified) approved by LRO Thermal Systems Lead. Mechanical thermostats shall be NASA GSFC S311-641 qualified and have an approved circuit design by the LRO Thermal Systems Lead.

**Table 3-3. Instrument Control Heater Power Allocations on the SC Instrument Operational Bus**

INSTRUMENT	HEATER POWER (W)		
	Operational	DeContam.	Survival
CRaTER	Sized by S/C	None	Sized by S/C
Diviner (on S/C isolated components only)	Provided separately via instrument power	None	16.4
Diviner Electronics	Sized by S/C	None	Sized by S/C
LROC NAC1	0	Separate Allocation	23
LROC NAC2	0	Separate Allocation	23
LROC WAC	6.9	Separate Allocation	8
LROC SCS	5.7	None	5.7
LAMP	6	Dissipated thru LAMP main power feed	10
LEND	Sized by S/C	None	Sized by S/C
LOLA Combined	27	None	54
Mini-RF	None	None	10

### 3.6 INSTRUMENT HEATER ALLOCATION (CONTROLLED BY COMPONENTS/INSTRUMENTS)

The instrument heater power allocation drawn from the internal instrument power bus is outlined in Table 3-5 as described in the individual instrument ICDs. The power shown is at 24V and is the size of the heater with GEVS margin 70% duty cycle. The power from these heaters will come directly out of the main instrument feeds and will only be operational when the instruments are turned on. Heaters shall be NASA GSFC S311-079 Kapton film heaters or Vishay Dale Ohm heaters (MIL-R-39009 Qualified) approved by LRO Thermal Systems Lead. Mechanical thermostats shall be NASA GSFC S311-641 qualified and have an approved circuit design by the LRO Thermal Systems Lead.

**Table 3-4. Instrument Control Heater Power Allocations Drawn from the Internal Instrument Power Bus**

INSTRUMENT	HEATER POWER (W)	
	Operational	DeContam.

INSTRUMENT	HEATER POWER (W)	
	Operational	DeContam.
CRaTER	None	None
Diviner	6	None
LROC NAC1	None	None
LROC NAC2	None	None
LROC WAC	None	None
LROC SCS	None	None
LAMP	None	1.4 W
LEND	4 max	None
LOLA Elec	None	None
LOLA Op Bench/Laser	None	None
LOLA TEC	3 max	None
Total	<b>13</b>	<b>1.4</b>

## **4.0 MULTI-LAYER INSULATION BLANKETS**

### **4.1 OUTER BLANKET COATING**

All exterior facing Multi-Layer Insulation (MLI) blankets in the avionics and instrument module area shall have a 3 mil Kapton with Vapor Deposited Aluminum (VDA) in outer coating unless approved by the LRO Thermal Systems Engineer Lead. There will be blankets in the propulsion module area that will need metallic shield outer layers.

### **4.2 MULTI-LAYER INSULATION BLANKET GROUNDING**

All blankets shall be grounded in accordance with the Lunar Reconnaissance Orbiter Electrical Systems Specification (431-ICD-000008).

### **4.3 MULTI-LAYER INSULATION BLANKET DOCUMENTATION**

All component MLI blankets shall have their location and shape documented in component as-built ICDs. All thermal subsystem MLI blankets shall be documented in the Lunar Reconnaissance Orbiter Project Electrical Systems Specification (431-SPEC-000008).

### **4.4 ATTACHMENT OF MULTI-LAYER INSULATION BLANKETS**

All exterior MLI blankets shall be mechanically constrained at least at one point or mechanically captured by another blanket or mechanical component.

## 5.0 THERMAL ANALYSIS

### 5.1 ENVIRONMENTAL CONDITIONS

#### 5.1.1 Thermal Conditions

The LRO environment is listed in Tables 5-1 and 5-2 below. MLI blankets shall be analyzed using an effective  $\varepsilon^*$  equal to 0.005 or 0.03 case specific that yields the worst case in the bounding thermal cases.

**Table 5-1. LRO Solar Constant and Albedo Factor**

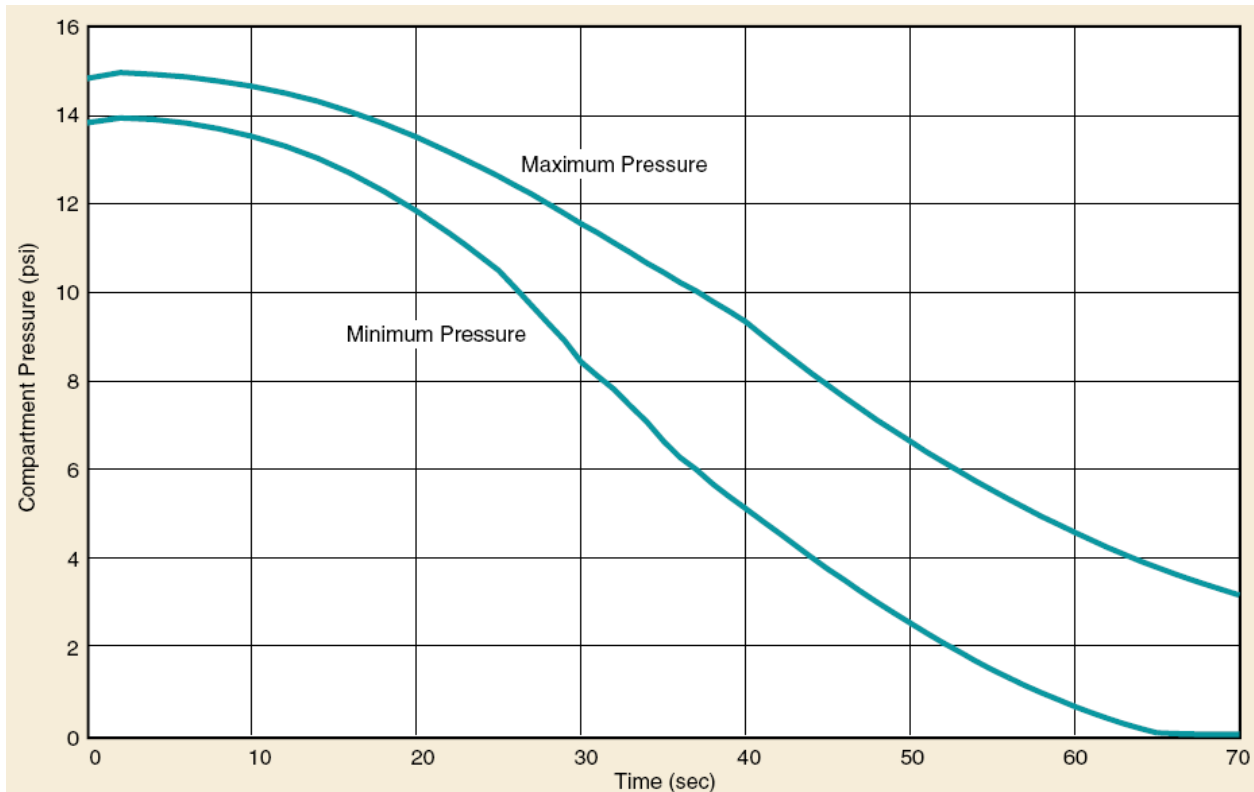
PARAMETER	Cold	Hot
Solar Constant	1280 W/m <sup>2</sup>	1420 W/m <sup>2</sup>
Albedo Factor	0.06	0.13

**Table 5-2. LRO Lunar Infrared**

ORBIT POSITION (°)	Beta $\theta^\circ$ (W/m <sup>2</sup> )	
	Hot	Cold
0 (sub-solar)	$(1335-5)*1*\text{COS}(\theta) + 5$	$(1114-5)*1*\text{COS}(\theta) + 5$
30	$(1335-5)*0.866*\text{COS}(\theta) + 5$	$(1114-5)*0.866*\text{COS}(\theta) + 5$
60	$(1335-5)*0.5*\text{COS}(\theta) + 5$	$(1114-5)*0.5*\text{COS}(\theta) + 5$
90	5	5
120	5	5
150	5	5
180	5	5
210	5	5
240	5	5
270	5	5
300	$(1335-5)*0.5*\text{COS}(\theta) + 5$	$(1114-5)*0.5*\text{COS}(\theta) + 5$
330	$(1335-5)*0.866*\text{COS}(\theta) + 5$	$(1114-5)*0.866*\text{COS}(\theta) + 5$
360 (sub-solar)	$(1335-5)*1*\text{COS}(\theta) + 5$	$(1114-5)*1*\text{COS}(\theta) + 5$

#### 5.1.2 Payload Fairing Ascent Pressure Profile

All MLI blankets and thermal hardware shall be built so that the rapid launch depressurization does not detach any thermal blankets or hardware (see Figure 5-1).



**Figure 5-1. Delta II-Like Fairing Pressure**

**5.2 THERMAL COATINGS**

**Table 5-3. LRO Thermal Coatings**

DESCRIPTION	COLD		HOT 14 mo. (5 yr.)		SPEC.	
	$\alpha_s$	$\epsilon_H$	$\alpha_s$	$\epsilon_H$	SOL	IR
<b>Coatings</b>						
Black Anodize Aluminum	0.7	0.82	0.86	0.78		
Clear Anodize	0.27	0.82	0.45	0.69		
Irridite Aluminum	0.10	0.19	0.57	0.06		
Z307 Conductive Black	0.95	0.89	0.97	0.85		
MSA94B Conductive Black	0.94	0.91	0.96	0.87		
Z306 Black Paint	0.94	0.89	0.95	0.85		
Z93P White Paint	0.17	0.92	0.25 (0.36)	0.87		

DESCRIPTION	COLD		HOT 14 mo. (5 yr.)		SPEC.	
	$\alpha_s$	$\epsilon_H$	$\alpha_s$	$\epsilon_H$	SOL	IR
NS43C Conductive White	0.20	0.91	0.26 (0.37)	0.87		
Vapor Deposited Aluminum	0.08	0.05	0.10	0.03	0.98	0.98
Vapor Deposited Gold	0.19	0.03	0.21	0.02		
<b>Films &amp; Tapes</b>						
Kapton, 3-mil/VDA backing	0.45	0.80	0.51 (0.60)	0.76	0.75	
OSR/ITO Pilkington, 5-mil	0.08	0.80	0.15 (0.23)	0.78	1.0	
ITO/Kapton/VDA 3 mil	0.46	0.80	0.51 (0.62)	0.76	0.75	
Black Kapton, 3-mil	0.91	0.81	0.93	0.78		
Germanium Black Kapton	0.49	0.81	0.51	0.78		
Silver Teflon ITO 5 mil (note that this is fragile and will require frequent replacement)	0.09	0.78	0.28 (0.37)	0.73	1.0	
<b>Miscellaneous</b>						
Solar Cell Triple Junction	0.86	0.87	0.90	0.77	1.0	---
M55J Composite, Bare	0.90	0.79	0.93	0.75		
K1100 Composite, Bare	0.88	0.73	0.88	0.69		
Fused Silica	<0.03	0.82	0.10	0.78		
BK7 Optical Glass	0.05	0.82	0.10	0.78		
Sapphire Lens	TBD	TBD	TBD	TBD		
Internal Fuel Line	1.0	0.15	1.0	0.15		
Machined Stainless Steel	0.39	0.18	0.47	0.14		
Hafnium	0.47	0.50	0.47	0.50		
Titanium Burnt	0.47	0.50	0.47	0.50		

### 5.3 HOT AND COLD BIAS OF POWER

Prior to the active measurement of operational power in a flight-like environment, all thermal design shall be able to handle a variation in each mode power on constant power components.



Powers to use in hot case and cold case shall be as follows: maximum power allocation in hot case, cold case minimum power dissipation current best estimate should be analyzed.

#### **5.4 MISSION MODES**

All components shall meet the appropriate survival or operational limits (component and mission mode specific) per Table 3-1 during all mission modes.

#### **5.5 THERMAL MODEL MARGIN**

Prior to flight, 5°C is the minimum required margin for model predictions with respect to Flight Operational Limits, except for heater controlled elements that demonstrate a maximum 70% heater duty cycle.

#### **5.6 THERMAL MODELING SCOPE**

The thermal modeling scope for LRO will be different than for other planetary mission's conventional wisdom. Transient analysis will be required to assess hot and cold cases. SC pointing tolerances may drive safe hold cases. Steady sun angles at high Beta angles may drive spatial gradient requirements. The responsible hardware manager shall examine all relevant environments assuming worst case pointing uncertainties in order to determine bounding thermal cases using Table 3-1 and direction as requested from the LRO Thermal Systems Lead.

#### **5.7 THERMAL ANALYSIS DOCUMENTATION**

All thermal analysis reports shall clearly outline all assumptions or source of assumptions. They shall detail the modeling technique used, details on the model, graphics and tables showing the temperature results versus requirements and discussion of what the results are sensitive to. It shall be clear what limitations the current analysis is subjected to and what future analyses are planned.

## **6.0 COMPONENT AND ORBITER INTEGRATION AND TEST**

The components and orbiter shall be tested in the bounding thermal cases in thermal vacuum. The target temperatures shall be specified as a result of a test model analysis. All thermal hardware shall comply with the Lunar Reconnaissance Orbiter Mechanical Systems Specification (431-SPEC-000012).

### **6.1 COMPONENT THERMAL CYCLING REQUIREMENT**

All components must be thermally cycled in a thermal vacuum chamber rather than in an air filled chamber. All components shall be flight like blanketed and cycled 8 times with the thermal interface held at the qualification temperatures listed above at the thermal interface. Durations shall be as recommended in GEVS: components 4 hours, instruments 12 hours. If the component is sensitive to orbit transience, component performance shall be monitored during hot to cold transitions at a rate that a flight like orbit average case might experience. Thermal Vacuum requirement can only be waived through approval of the LRO Thermal Systems Lead.

### **6.2 MODEL DOCUMENTATION**

The Reduced Geometric Math Models (RGMMs) and Reduced Thermal Math Models (RTMMs) delivered to GSFC shall be accompanied by appropriate model documentation as specified in the Lunar Reconnaissance Orbiter Thermal Math Model Requirements (431-RQMT-000092) document.

### **6.3 COMPONENT THERMAL TEST MODEL**

All thermal tests shall be Thermal Synthesizer System (TSS)/System Improved Numerical Differencing Analyzer (SINDA) modeled prior to starting the test to derive target temperatures. Target temperatures shall achieve heat flows and effective sink temperatures that closely resemble the flight environment. An analysis report shall be issued which outlines the derivation of the target temperatures. This analysis report should outline all cases that will be assessed in thermal vacuum (i.e. hot case steady state, hot transient, cold steady state, survival, etc.)

### **6.4 COMPONENT THERMAL TEST DOCUMENTATION**

All final thermal qualification test plan shall be approved by the LRO Thermal Systems Lead. Target temperatures and overall test setup shall be discussed with the LRO Thermal Systems Lead.

### **6.5 THERMAL MODEL CORRELATION**

All models shall be correlated within 2°C of every telemetry point with the thermal test model. The thermal test model shall then be reintegrated into the flight model.

## **6.6 REDUCED MODEL**

Reduced component models shall be made available to the thermal team 30 days before the Preliminary Design Review (PDR), Critical Design Review (CDR), Pre-Environmental Review (PER), and delivery to Orbiter Integration and Test (I&T). Models requested earlier than this requirement shall be used to pass back to components as bounding system reduced models for component reviews and therefore their delivery dates shall be based on 45 days before the first component review. These models shall utilize the latest known power levels and mechanical configuration. The models shall be correlated with any qualification testing. The reduced model shall be delivered in accordance with the Lunar Reconnaissance Orbiter Thermal Math Model Requirements (431-RQMT-000092).

## **6.7 IN-AIR THERMAL CONTROL**

All instruments shall be capable of operating within an ambient air temperature of  $20\pm 5^{\circ}\text{C}$  without degrading instrument performance. No active cooling shall be provided during instrument operation with or without blanket covering. Allowance in the instrument blanket design may be utilized to open higher heat flux areas of the instrument to the surrounding ambient air, but the blanket design shall accommodate opening and closing without blanket damage.

## **6.8 ORBITER THERMAL VACUUM/BALANCE LEVELNESS AND ORIENTATION REQUIREMENTS**

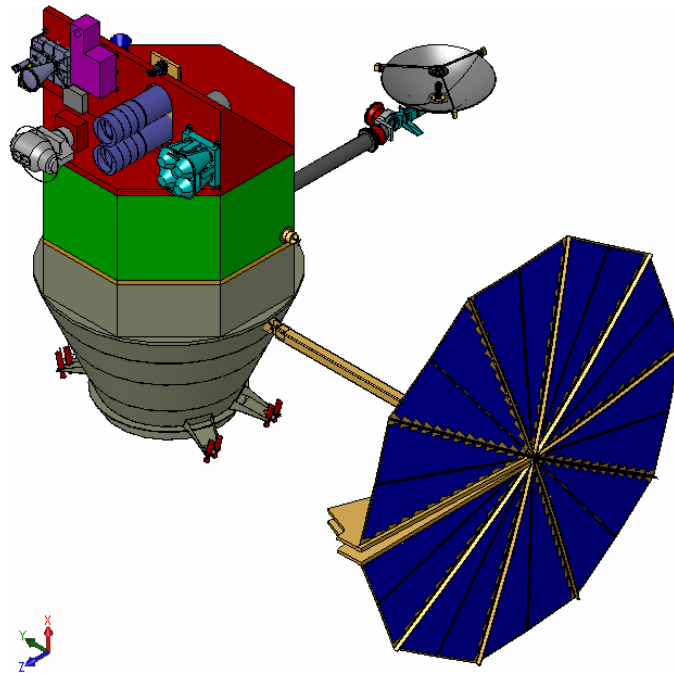
All instruments shall be capable of operating within a thermal vacuum chamber with flight like thermal environment based on the instrument reduced models provided. The horizontal plane will be the X and Y axes with instrument viewing nadir down. There is no known sensitivity to the gravity vector for proper operation during this test of any non-thermal component. Heat Pipes, if they are utilized, will require no more than a  $\pm 0.1^{\circ}/2$  meter tilt in any one location from the horizontal plane.

## **6.9 LUNAR RECONNAISSANCE ORBITER COORDINATE SYSTEM**

The LRO mechanical and thermal coordinate system is shown in Figure 6-1. Unless otherwise noted, this document shall refer to the LRO coordinate system.

## **6.10 TEST HEATERS**

During Orbiter thermal vacuum (TVAC) testing, the configuration of the Orbiter in the vicinity of each component may not be flight like due to placement heater panels and cold plates. The effective sink temperature for some components may be colder than during the mission. Each responsible hardware manager shall anticipate, to the extent possible, such possibilities and provide test heaters in coordination with the LRO Thermal Systems Lead. Prior to component I&T the responsible hardware manager in coordination with the LRO Thermal Systems Lead shall make a determination of whether test heaters will be required.



**Figure 6-1. LRO Coordinate System Definition**

In such cases, the responsible hardware manager shall supply their own test heaters, cabling and means of control (**TBR**). Any such heaters shall be mounted on the component, not the SC. The component team shall install and control any such test heaters, as needed, to maintain the temperatures of the instrument within the survival range during TVAC.

Heater leads should be of sufficient length to allow connection to test chamber heater harnesses.

## 6.11 TEST SENSORS

Test sensors required to verify proper operation of the component during orbiter thermal vacuum testing shall be installed prior to deliver of the component. These sensors shall be identified on as-built drawings using orbiter approved test sensors. A plan shall be also submitted to remove some or all of these sensors before flight. The test sensors that may be read at orbiter thermal vacuum testing will be limited or reduced by the LRO Thermal Systems Lead to meet the test setup requirements.

**Appendix A. Abbreviations and Acronyms**

<b>Abbreviation/ Acronym</b>	<b>DEFINITION</b>
ACS	Attitude Control System
°C	Degrees Centigrade
C&DH	Command and Data Handling
CBE	Current Best Estimate
CCB	Configuration Control Board
CCR	Configuration Change Request
CDR	Critical Design Review
CM	Configuration Management
CMO	Configuration Management Office
CRaTER	Cosmic Ray Telescope of the Effects of Radiation
Diviner	Diviner Instrument
ELV	Expendable Launch Vehicle
EPC	Electrical Power Conditioner
EVD	Engine Valve Driver
GEVS	General Environmental Verification Standards
GSFC	Goddard Space Flight Center
HGA	High Gain Antenna
HKIO	House Keeping Input Output
Htrs	Heaters
I&T	Integration and Test
I/F	Interface
ICD	Interface Control Document
IR	Infrared
IMU	Inertial Measurement Unit
Km	Kilometer
LAMP	Lyman-Alpha Mapping Project
LEND	Lunar Exploration Neutron Detector
LOLA	Lunar Orbiter Laser Altimeter
LROC	Lunar Reconnaissance Orbiter Camera
LRO	Lunar Reconnaissance Orbiter
LVPC	Low Voltage Power Converter
Max.	Maximum
Min.	Minimum
MLI	Multi-Layer Insulation
Mo.	Months
MTG	Mounting
N/A	Not Applicable
NAC	Narrow Angle Camera

A-1

CHECK WITH ~~RLEP-LRO~~ DATABASE AT:  
<https://lunarngin.gsfc.nasa.gov>  
 TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

<b>Abbreviation/ Acronym</b>	<b>DEFINITION</b>
NASA	National Aeronautics and Space Administration
NC	Normally Closed
OP	Operational
PDE	Propulsion and Deployable Electronics
PDR	Preliminary Design Review
PER	Pre-Environmental Review
PRT	Platinum Resistance Thermistor
PSE	Power Subsystem Electronics
Psi	Pounds per square inch
Pts	Points
Pwr	Power
RF	Radio Frequency
RGMM	Reduced Geometric Math Model
RTMM	Reduced Thermal Math Model
RWA	Reaction Wheel Assembly
S/A	Solar Array
SBC	Single Board Computer
SC	Spacecraft
SCS	Sequencing and Compressor System
Sec.	Seconds
SINDA	Systems Improved Numerical Differencing Analyzer
SOL	Solar
Spec.	Spectularity
SSR	Solid State Recorder
STS	Space Transportation System
TBD	To Be Determined
TBR	To Be Reviewed
TSS	Thermal Synthesizer System
TT&C	Telemetry Tracking and Control
TWTA	Traveling Wave Tube Amplifier
USB	Universal System Bus
VDA	Vapor Deposited Aluminum
W	Watt
w/o	Without
W/cm <sup>2</sup>	Watts per centimeter squared
W/in <sup>2</sup>	Watts per inch squared
W/m <sup>2</sup>	Watts per meter squared
WAC	Wide Angle Camera
XPDR	Transponder
V	Volt(s)

